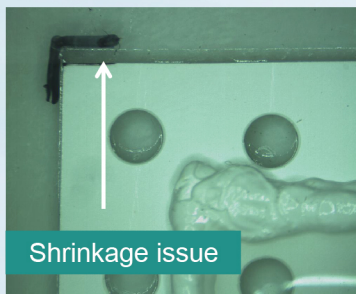


长兴 Mini LED 封装胶低温 / UV 固化方案

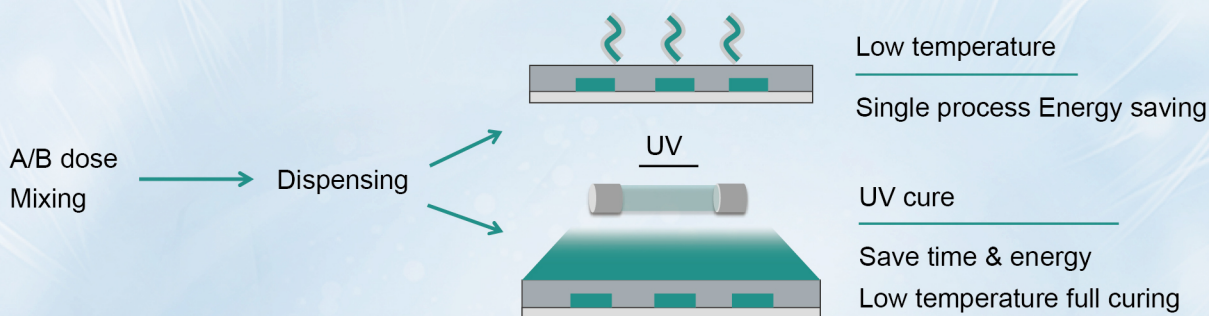
Silicone Material For Encapsulation

1 封装制程痛点 problem & Issue:

- ◆ 高温长时间烘烤易使非耐热基材收缩及翘曲

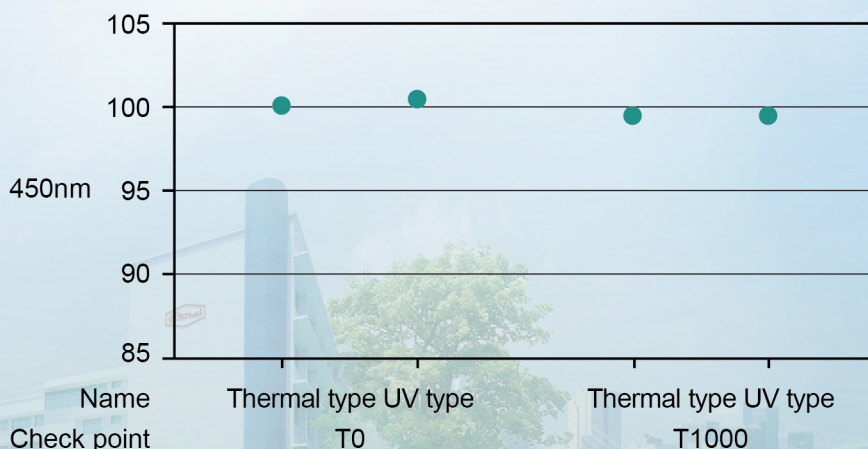


2 低温/UV固化解决方案 Low T & UV curing solution:



3 良好的耐温特性 HT Reliability Performance:

- ◆ 高温高湿 (85°C/85%) 信赖性测试后, 仍有良好穿透性能



长兴透镜型 Mini LED 硅胶封装胶方案

Lens Type Silicone Material For Encapsulation

1 简介 Introduction:

光学级透镜胶, 适合用于 Mini LED 中大型面板封装, 可提高LED光萃取率并节省封装用胶量。

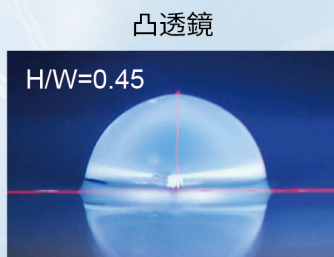
Optical silicone lens, suitable for encapsulation of medium and large panels of Mini LED, can improve LED light extraction and save the quantity of material consumption.

2 特性 Characterizes:

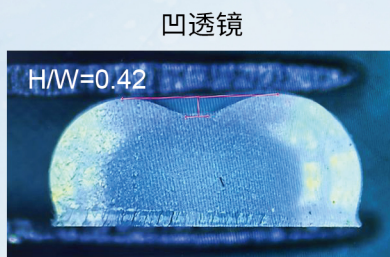
- ▶ 光学透明度佳 High optical transmittance
- ▶ 高触变性 High thixotropic index
- ▶ 成形稳定性佳 High forming stability
- ▶ 抗裂性佳 High anti-crack capability
- ▶ 耐温性佳 Resistant to high and low temperatures
- ▶ 封装用胶量少 Low material consumption

3 应用测试 Application test:

◎ 成形高宽 Lens H/W ratio



H=0.97mm, W=2.15mm



H=2.0mm, W=4.8mm

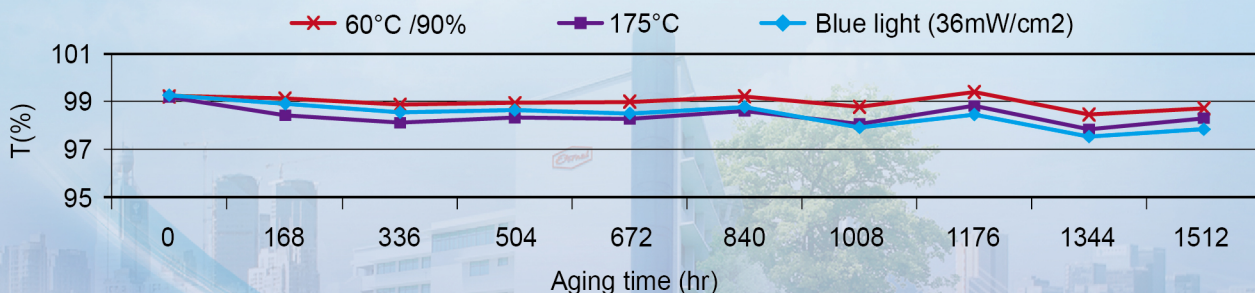


H=1.3mm, W=4.6mm

◎ 信赖性表现 Reliability performance

300 um thickness on glass

T% @ 450 nm



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长兴 Mini/Micro-LED 封装硅胶膜方案

Silicone Film For Mini/Micro-LED Encapsulation

1 简介 Introduction:

光学级硅胶膜, 适合用于 Mini/Micro-LED 封装, 具高透光度、高耐候性、优异的抗裂性、高封装效率、高封装一致性。

Optical silicone lens, suitable for encapsulation of medium and large panels of Mini LED, can improve LED light extraction and save the quantity of material consumption.

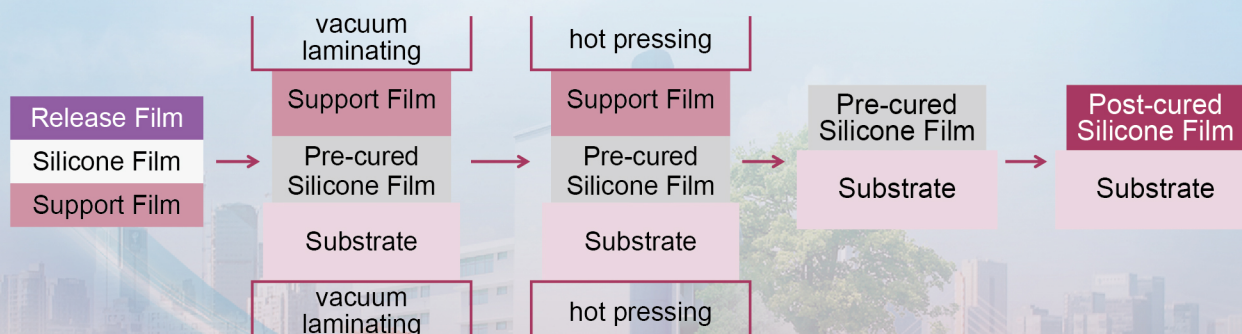
2 特性 Characterizes:

- ▶ 光学透明度佳 High optical transmittance
- ▶ 耐温性佳 Resistant to high and low temperatures
- ▶ 粘著力与接著力佳 Good adhesion to substrate
- ▶ 封装效率高 High encapsulant efficiency
- ▶ 抗裂性佳 High anti-crack capability
- ▶ 封装一致性高 High encapsulant consistency

3 产品 Product:



4 制程方法 Process & Method:



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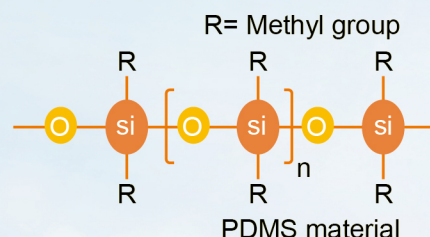
长兴巨量微型转印 PDMS 材料方案

Micro/Mini LED Mass Transfer PDMS Stamp

1 简介 Introduction:

转印印章法以范德华力及转印之速度差异，黏附晶粒并转移至目标基板 具有良好的初黏力及耐热性。

PDMS materials for mass transfer stamp method have excellent heat resistance and surface tack properties to pick up micro-LED chips by Van der waals force, and can detach from PDMS stamp to substrate.



2 特性 Characterizes:

▶ 初期粘著力佳

Good surface tack to micro device

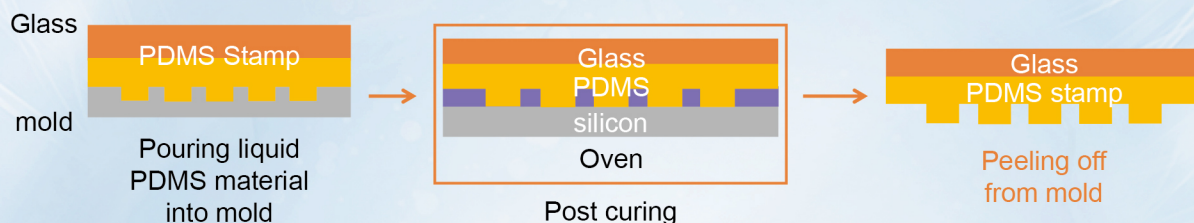
▶ 脱模性佳

Easy to demold from wafer

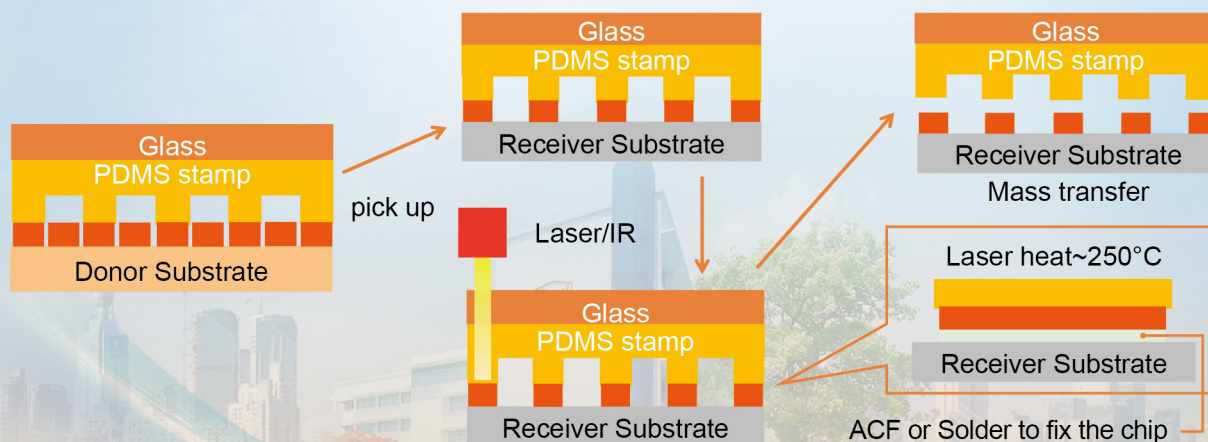
▶ 耐高温性佳

Resistant to high and low temperatures

3 制程方法 Process & Method:



4 应用 Applications:



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